

# GP-1 Cu Heavy Bonding Wire for Power Device

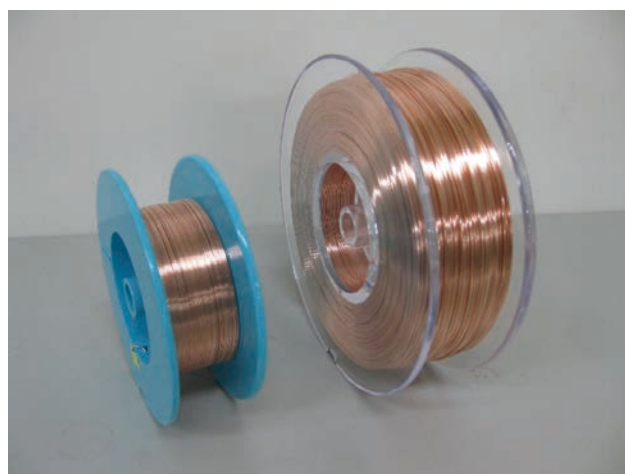
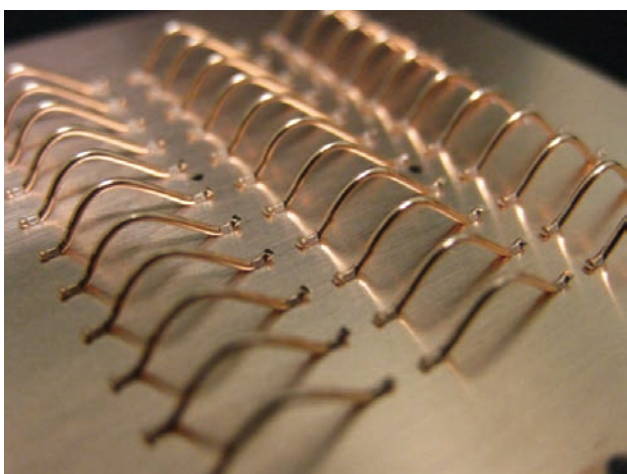
## パワーデバイス用Cuボンディングワイヤ

### Characteristics

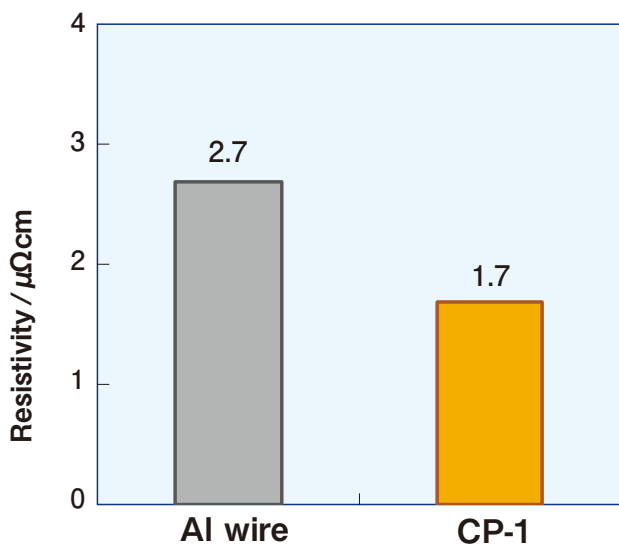
- Excellent electrical conductivity (40% higher than Al)
- High fusing current (30% higher than Al)

### 特 徴

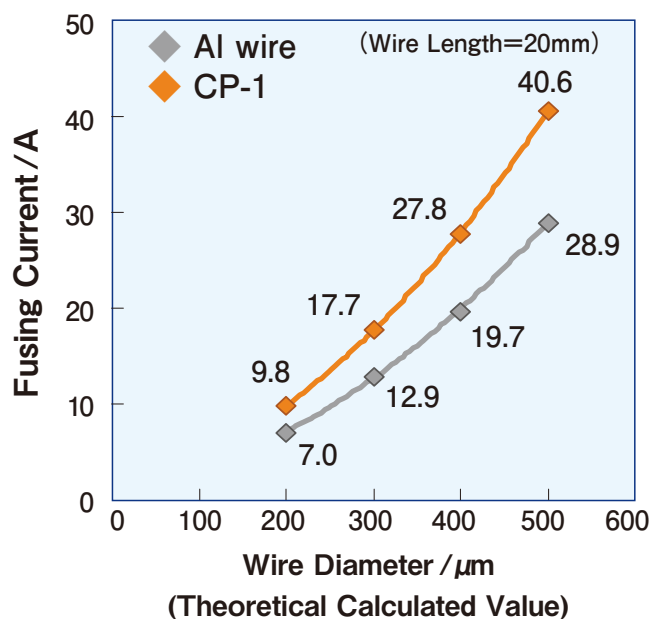
- 優れた電気伝導性 (40% higher than Al)
- 優れた溶断電流 (30% higher than Al)



### Resistivity



### Fusing Current



# CP-1 Data Sheet

## General Properties

Wire Diameter (um)	<b>200</b>	<b>250</b>	<b>300</b>	<b>350</b>	<b>380</b>	<b>400</b>	<b>450</b>	<b>500</b>
Tolerance (um)	+/- 7.0							+/- 10.0
Breaking Load (gf)	510-917	816-1427	1326-2039	1734-2651	2040-3059	2346-3365	3264-4282	4079-5302
Elongation (%)	5.0 - 35.0			10.0 - 40.0				10.0-50.0
maximum winding length (m)	300							200

## Physical Property

Hardness (HV)	Wire	60 - 80							
Density (g/cm <sup>3</sup> )		8.92							
Resistivity (uΩ cm) @ 20°C		1.7							
Fusing Current (A, Length=10mm,10sec)		8.8	14	20	27	32	35	44	55
Electrical resistance (mΩ, Length 10mm, Room Temp.)		5.1 - 5.8	3.3 - 3.7	2.3 - 2.5	1.7 - 1.8	1.4 - 1.6	1.3 - 1.4	1.0 - 1.1	0.8 - 0.9
Thermal Conductivity @ 20°C (W/m/K)		431							
Linear Expansion Coefficient (0-100°C) (ppm/K)		17.0							
Elastic Modulus (GPa)		80 - 100							
Melting Point (°C)		1,083							